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BGA2874

MMIC wideband amplifier

Rev. 3 — 3 October 2016

Product data sheet

1. Product profile

1.1 General description

Silicon Monolithic Microwave Integrated Circuit (MMIC) wideband amplifier with internal matching circuit in a 6-pin SOT363 plastic SMD package.

1.2 Features and benefits

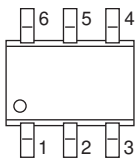
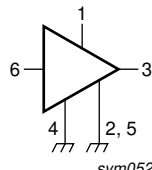
- Internally matched to $50\ \Omega$
- A gain of 31.0 dB at 750 MHz
- Output power at 1 dB gain compression = 5 dBm
- Supply current = 16.5 mA at a supply voltage of 2.5 V
- Reverse isolation > 52 dB up to 750 MHz
- Good linearity with low second order and third order products
- Noise figure = 3.1 dB at 500 MHz
- Unconditionally stable ($K > 1$)
- No output inductor required

1.3 Applications

- LNB IF amplifiers
- General purpose low noise wideband amplifier for frequencies between DC and 750 MHz

2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	V_{CC}		 sym052
2, 5	GND2		
3	RF_OUT		
4	GND1		
6	RF_IN		



3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BGA2874	-	plastic surface-mounted package; 6 leads	SOT363

4. Marking

Table 3. Marking

Type number	Marking code	Description
BGA2874	LR*	* = - : made in Hong Kong
		* = p : made in Hong Kong
		* = W : made in China
		* = t : made in Malaysia

5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage	RF input AC coupled	-0.5	+3.6	V
I_{CC}	supply current		-	55	mA
P_{tot}	total power dissipation	$T_{sp} = 90\text{ °C}$	-	200	mW
T_{stg}	storage temperature		-40	+125	°C
T_j	junction temperature		-	125	°C
P_{drive}	drive power		-	+10	dBm

6. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	$P_{tot} = 200\text{ mW}$; $T_{sp} = 90\text{ °C}$	300	K/W

7. Characteristics

Table 6. Characteristics

$V_{CC} = 2.5\text{ V}$; $Z_S = Z_L = 50\text{ }\Omega$; $P_i = -40\text{ dBm}$; $T_{amb} = 25\text{ °C}$; measured on demo board; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		2.3	2.5	2.7	V
I_{CC}	supply current		14.0	16.5	19.0	mA

Table 6. Characteristics ...continued

$V_{CC} = 2.5\text{ V}$; $Z_S = Z_L = 50\ \Omega$; $P_i = -40\text{ dBm}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$; measured on demo board; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
G_p	power gain	$f = 250\text{ MHz}$	30.5	31.1	31.7	dB
		$f = 500\text{ MHz}$	30.4	31.0	31.6	dB
		$f = 750\text{ MHz}$	29.9	30.6	31.3	dB
RL_{in}	input return loss	$f = 250\text{ MHz}$	25	27	29	dB
		$f = 500\text{ MHz}$	19	21	23	dB
		$f = 750\text{ MHz}$	15	17	19	dB
RL_{out}	output return loss	$f = 250\text{ MHz}$	19	23	28	dB
		$f = 500\text{ MHz}$	18	22	27	dB
		$f = 750\text{ MHz}$	17	18	19	dB
ISL	isolation	$f = 250\text{ MHz}$	43	64	84	dB
		$f = 500\text{ MHz}$	57	58	60	dB
		$f = 750\text{ MHz}$	49	52	54	dB
NF	noise figure	$f = 250\text{ MHz}$	2.6	3.0	3.5	dB
		$f = 500\text{ MHz}$	2.6	3.1	3.6	dB
		$f = 750\text{ MHz}$	3.0	3.4	3.8	dB
B_{-3dB}	-3 dB bandwidth	3 dB below gain at 1 GHz	1.8	2.0	2.2	GHz
K	Rollett stability factor	$f = 250\text{ MHz}$	14	21	29	
		$f = 500\text{ MHz}$	8	12	16	
		$f = 750\text{ MHz}$	4	5	6	
$P_{L(sat)}$	saturated output power	$f = 250\text{ MHz}$	5	6	7	dBm
		$f = 500\text{ MHz}$	4	5	6	dBm
		$f = 750\text{ MHz}$	3	4	6	dBm
$P_{L(1dB)}$	output power at 1 dB gain compression	$f = 250\text{ MHz}$	5	5	6	dBm
		$f = 500\text{ MHz}$	4	5	6	dBm
		$f = 750\text{ MHz}$	3	4	5	dBm
$IP3_I$	input third-order intercept point	$P_{drive} = -45\text{ dBm}$ (for each tone)				
		$f_1 = 250\text{ MHz}; f_2 = 251\text{ MHz}$	-14	-12	-10	dBm
		$f_1 = 500\text{ MHz}; f_2 = 501\text{ MHz}$	-15	-13	-11	dBm
		$f_1 = 750\text{ MHz}; f_2 = 751\text{ MHz}$	-16	-13	-11	dBm
$IP3_O$	output third-order intercept point	$P_{drive} = -45\text{ dBm}$ (for each tone)				
		$f_1 = 250\text{ MHz}; f_2 = 251\text{ MHz}$	17	19	21	dBm
		$f_1 = 500\text{ MHz}; f_2 = 501\text{ MHz}$	16	18	20	dBm
		$f_1 = 750\text{ MHz}; f_2 = 751\text{ MHz}$	15	17	19	dBm
$P_{L(2H)}$	second harmonic output power	$P_{drive} = -42\text{ dBm}$				
		$f_{1H} = 250\text{ MHz}; f_{2H} = 500\text{ MHz}$	-58	-56	-54	dBm
		$f_{1H} = 500\text{ MHz}; f_{2H} = 1900\text{ MHz}$	-	-51	-	dBm
$\Delta IM2$	second-order intermodulation distance	$P_{drive} = -45\text{ dBm}$ (for each tone)				
		$f_1 = 250\text{ MHz}; f_2 = 251\text{ MHz}$	52	54	57	dBc
		$f_1 = 500\text{ MHz}; f_2 = 501\text{ MHz}$	-	47	-	dBc

8. Application information

Figure 1 shows a typical application circuit for the BGA2874 MMIC. The device is internally matched to 50 Ω , and therefore does not need any external matching. The value of the input and output DC blocking capacitors C2 and C3 should not be more than 100 pF for applications above 100 MHz. However, when the device is operated below 100 MHz, the capacitor value should be increased.

The 22 nF supply decoupling capacitor C1 should be located as close as possible to the MMIC.

The PCB top ground plane, connected to pins 2, 4 and 5 must be as close as possible to the MMIC, preferably also below the MMIC. When using via holes, use multiple via holes as close as possible to the MMIC.

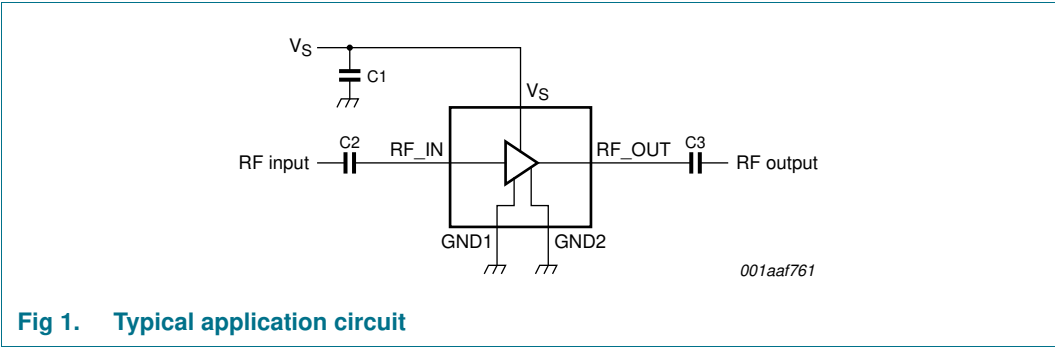


Fig 1. Typical application circuit

8.1 Application examples

The MMIC is very suitable as IF amplifier in e.g. LNB's. The excellent wideband characteristics make it an easy building block.

As second amplifier after an LNA, the MMIC offers an easy matching, low noise solution.

8.2 Tables

Table 7. Supply current over temperature and supply voltages
Typical values.

Symbol	Parameter	Conditions	T _{amb} (°C)			Unit
			−40	+25	+85	
I _{CC}	supply current	V _{CC} = 2.3 V	14.90	14.50	14.10	mA
		V _{CC} = 2.5 V	17.20	16.50	16.10	mA
		V _{CC} = 2.7 V	19.10	18.40	17.80	mA

Table 8. Second harmonic output power over temperature and supply voltages*Typical values.*

Symbol	Parameter	Conditions	T _{amb} (°C)			Unit
			-40	+25	+85	
P _{L(2H)}	second harmonic output power	f = 250 MHz; P _{drive} = -42 dBm				
		V _{CC} = 2.3 V	-51	-55	-59	dBm
		V _{CC} = 2.5 V	-53	-56	-59	dBm
		V _{CC} = 2.7 V	-54	-56	-60	dBm
		f = 500 MHz; P _{drive} = -42 dBm				
		V _{CC} = 2.3 V	-49	-51	-52	dBm
		V _{CC} = 2.5 V	-49	-51	-52	dBm
		V _{CC} = 2.7 V	-49	-51	-52	dBm

Table 9. Input power at 1 dB gain compression over temperature and supply voltages*Typical values.*

Symbol	Parameter	Conditions	T _{amb} (°C)			Unit
			-40	+25	+85	
P _{I(1dB)}	input power at 1 dB gain compression	f = 250 MHz				
		V _{CC} = 2.3 V	-24	-24	-25	dBm
		V _{CC} = 2.5 V	-25	-25	-25	dBm
		V _{CC} = 2.7 V	-25	-25	-25	dBm
		f = 500 MHz				
		V _{CC} = 2.3 V	-24	-25	-25	dBm
		V _{CC} = 2.5 V	-25	-25	-25	dBm
		V _{CC} = 2.7 V	-25	-25	-25	dBm
		f = 750 MHz				
		V _{CC} = 2.3 V	-24	-25	-26	dBm
		V _{CC} = 2.5 V	-25	-25	-26	dBm
		V _{CC} = 2.7 V	-25	-25	-26	dBm

Table 10. Output power at 1 dB gain compression over temperature and supply voltages
Typical values.

Symbol	Parameter	Conditions	T _{amb} (°C)			Unit
			-40	+25	+85	
P _{L(1dB)}	output power at 1 dB gain compression	f = 250 MHz				
		V _{CC} = 2.3 V	4	5	4	dBm
		V _{CC} = 2.5 V	5	5	5	dBm
		V _{CC} = 2.7 V	6	6	5	dBm
		f = 500 MHz				
		V _{CC} = 2.3 V	4	4	3	dBm
		V _{CC} = 2.5 V	5	5	4	dBm
		V _{CC} = 2.7 V	6	5	5	dBm
		f = 750 MHz				
		V _{CC} = 2.3 V	3	3	2	dBm
		V _{CC} = 2.5 V	5	4	3	dBm
		V _{CC} = 2.7 V	5	5	4	dBm

Table 11. Saturated output power over temperature and supply voltages
Typical values.

Symbol	Parameter	Conditions	T _{amb} (°C)			Unit
			-40	+25	+85	
P _{L(sat)}	saturated output power	f = 250 MHz				
		V _{CC} = 2.3 V	5	5	5	dBm
		V _{CC} = 2.5 V	6	6	6	dBm
		V _{CC} = 2.7 V	7	7	7	dBm
		f = 500 MHz				
		V _{CC} = 2.3 V	4	4	4	dBm
		V _{CC} = 2.5 V	5	5	5	dBm
		V _{CC} = 2.7 V	6	6	5	dBm
		f = 750 MHz				
		V _{CC} = 2.3 V	4	4	3	dBm
		V _{CC} = 2.5 V	5	4	4	dBm
		V _{CC} = 2.7 V	5	5	5	dBm

Table 12. Second-order intermodulation distance over temperature and supply voltages
Typical values.

Symbol	Parameter	Conditions	T _{amb} (°C)			Unit
			–40	+25	+85	
ΔIM2	second-order intermodulation distance	f ₁ = 250 MHz; f ₂ = 251 MHz; P _{drive} = –45 dBm				
		V _{CC} = 2.3 V	42	54	50	dBc
		V _{CC} = 2.5 V	52	54	48	dBc
		V _{CC} = 2.7 V	58	52	48	dBc
		f ₁ = 500 MHz; f ₂ = 501 MHz; P _{drive} = –45 dBm				
		V _{CC} = 2.3 V	42	48	44	dBc
		V _{CC} = 2.5 V	48	47	43	dBc
		V _{CC} = 2.7 V	50	47	43	dBc

Table 13. Output third-order intercept point over temperature and supply voltages
Typical values.

Symbol	Parameter	Conditions	T _{amb} (°C)			Unit
			–40	+25	+85	
IP3 _O	output third-order intercept point	f ₁ = 250 MHz; f ₂ = 251 MHz; P _{drive} = –45 dBm				
		V _{CC} = 2.3 V	18	18	17	dBm
		V _{CC} = 2.5 V	20	19	18	dBm
		V _{CC} = 2.7 V	21	20	18	dBm
		f ₁ = 500 MHz; f ₂ = 501 MHz; P _{drive} = –45 dBm				
		V _{CC} = 2.3 V	19	17	15	dBm
		V _{CC} = 2.5 V	20	18	16	dBm
		V _{CC} = 2.7 V	20	18	16	dBm
		f ₁ = 750 MHz; f ₂ = 751 MHz; P _{drive} = –45 dBm				
		V _{CC} = 2.3 V	19	16	14	dBm
		V _{CC} = 2.5 V	19	17	14	dBm
		V _{CC} = 2.7 V	20	17	15	dBm

Table 14. –3 dB bandwidth over temperature and supply voltages
Typical values.

Symbol	Parameter	Conditions	T _{amb} (°C)			Unit
			–40	+25	+85	
B _{–3dB}	–3 dB bandwidth	V _{CC} = 2.3 V	2.04	1.98	1.89	GHz
		V _{CC} = 2.5 V	2.05	1.98	1.89	GHz
		V _{CC} = 2.7 V	2.06	1.99	1.89	GHz

9. Test information

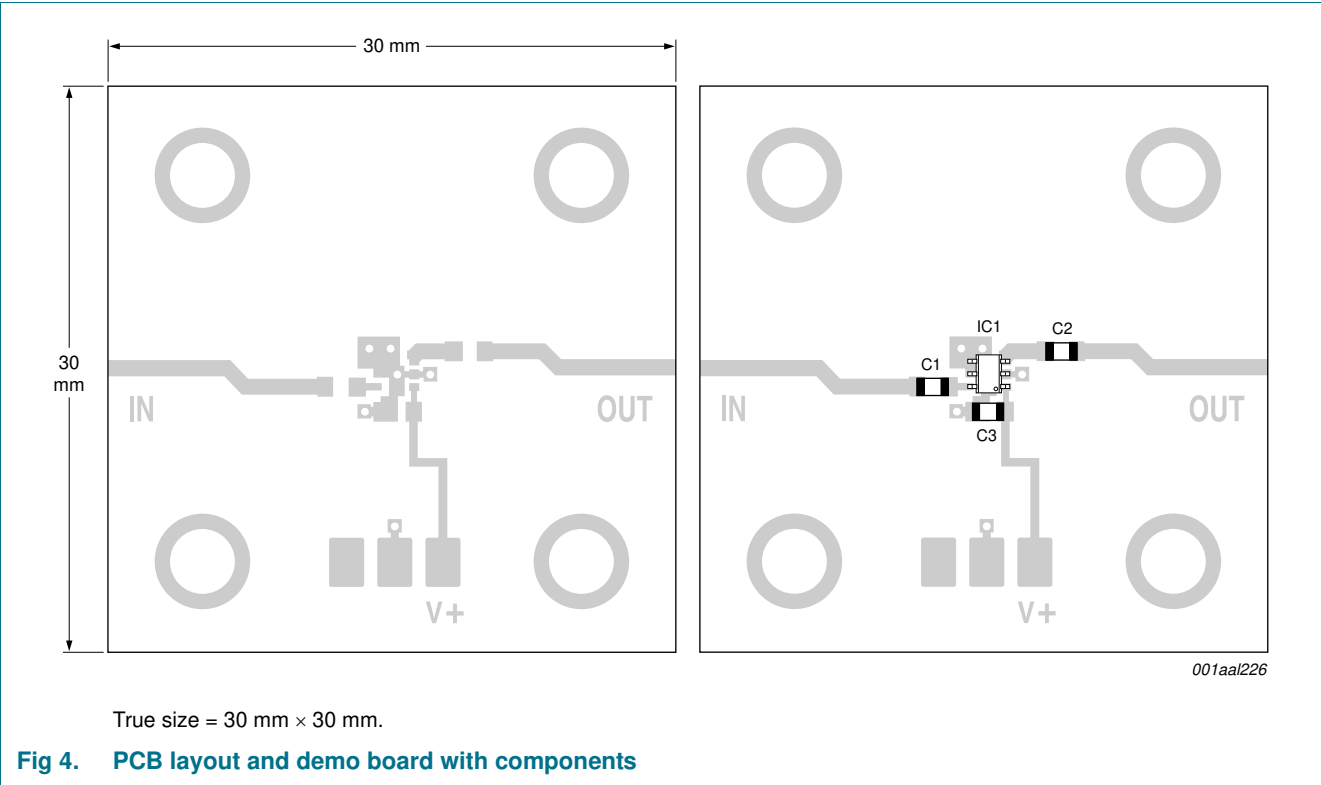


Table 15. List of components used for the typical application

Component	Description	Value	Dimensions
C1, C2	multilayer ceramic chip capacitor	100 pF	0603
C3	multilayer ceramic chip capacitor	22 nF	0603
IC1	BGA2874 MMIC	-	SOT363

10. Package outline

Plastic surface-mounted package; 6 leads

SOT363

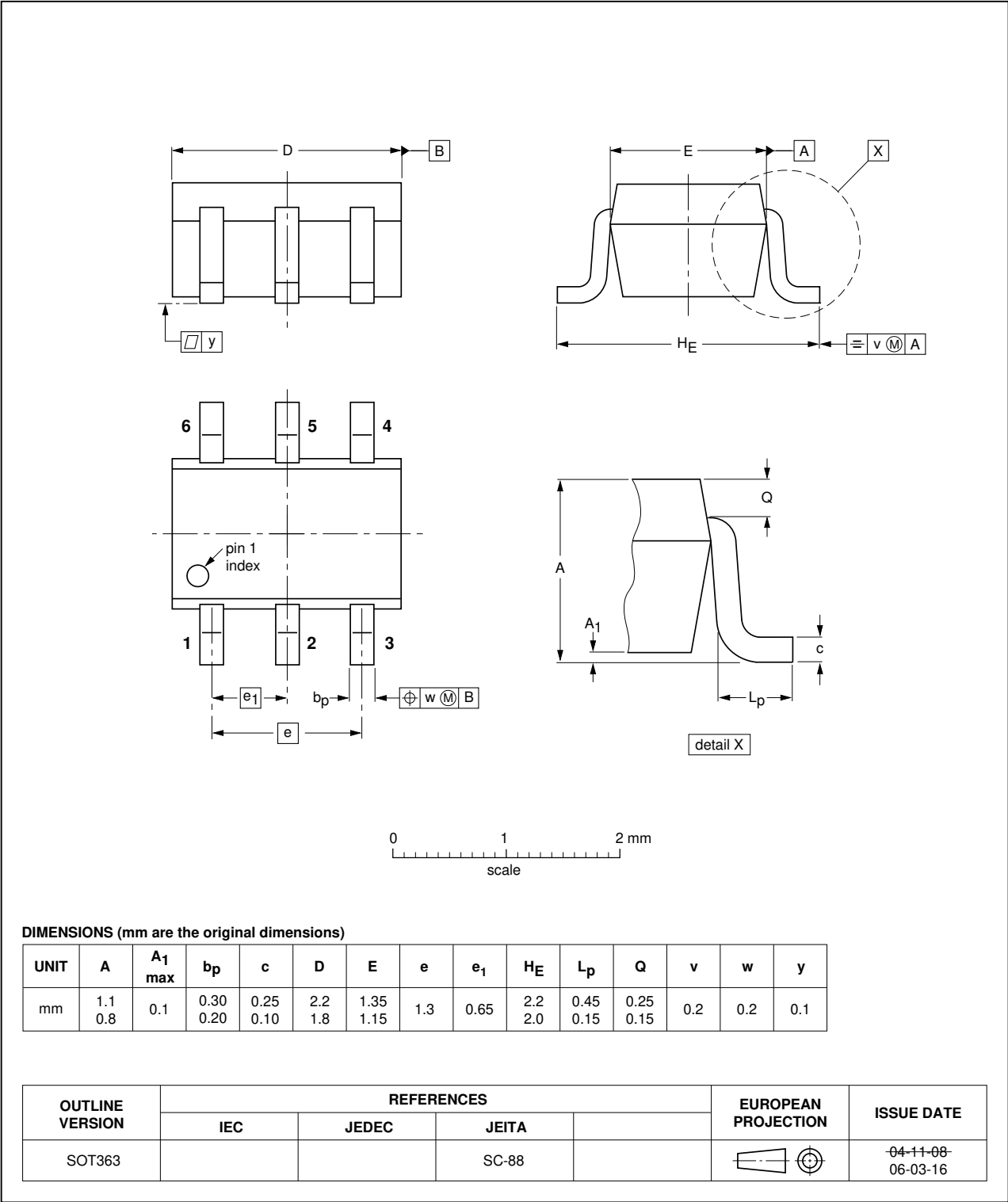


Fig 5. Package outline SOT363

11. Abbreviations

Table 16. Abbreviations

Acronym	Description
DC	Direct Current
IF	Intermediate Frequency
LNA	Low-Noise Amplifier
LNB	Low-Noise Block converter
PCB	Printed-Circuit Board
RF	Radio Frequency
SMD	Surface Mounted Device

12. Revision history

Table 17. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BGA2874 v.3	20161003	Product data sheet		BGA2874 v.2
Modifications:	<ul style="list-style-type: none">Table 6 on page 2: the min/max value for $P_{L(2H)}$ ($f_{1H} = 500 \text{ MHz}$; $f_{2H} = 1900 \text{ MHz}$) removedTable 6 on page 2: the min/max value for $\Delta IM2$ ($f_1 = 500 \text{ MHz}$; $f_2 = 501 \text{ MHz}$) removed			
BGA2874 v.2	20150710	Product data sheet	-	BGA2874 v.1
Modifications:	<ul style="list-style-type: none">The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.Legal texts have been adapted to the new company name where appropriate.			
BGA2874 v.1	20111223	Product data sheet	-	-

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Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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[2] The term 'short data sheet' is explained in section "Definitions".

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